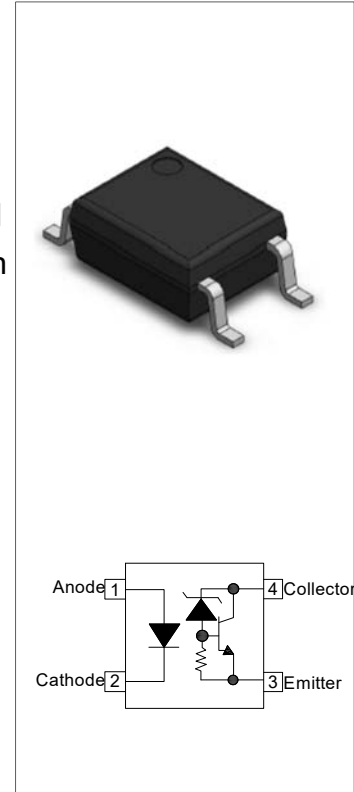


### DESCRIPTION:

The products are transistor output opto-couplers in a plastic SOP4 package. The device which is infrared LED chip and Photo-transistor chip are assembled on lead frame, in order to change the electricity-light-electricity. The products are widely used in transmission and conversion of digital logic, power control and switch, electric insulation and impedance conversion between circuits systems.



### MAIN FEATURES

- High isolation 3750 VRMS
- Operating temperature range -40°C to 110°C
- RoHS & REACH Compliance
- HBM: H3A; MM: M4; CDM:C3
- CQC approved
- VDE approved
- UL approved

### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1 <sup>①</sup>	A
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P_D$	75	mW
Output	Collector-emitter Voltage	$V_{CEO}$	40	V
	Emitter-collector Voltage	$V_{ECO}$	7	V
	Collector Current	$I_C$	50	mA
	Power Dissipation	$P_C$	150	mW
Total Power Dissipation		$P_{tot}$	225	mW
Isolation Voltage		$V_{iso}$	3750 <sup>②</sup>	Vrms
Operating Temperature		$T_{opr}$	-40~+110	°C
Junction Temperature		$T_j$	125	°C

Storage Temperature	T <sub>stg</sub>	-55~+125	°C
Soldering Temperature	T <sub>sol</sub>	260	°C

**NOTE1:** 100μs pulse, 100Hz frequency

**NOTE2:** AC for 1minute, R.H.=40~60%

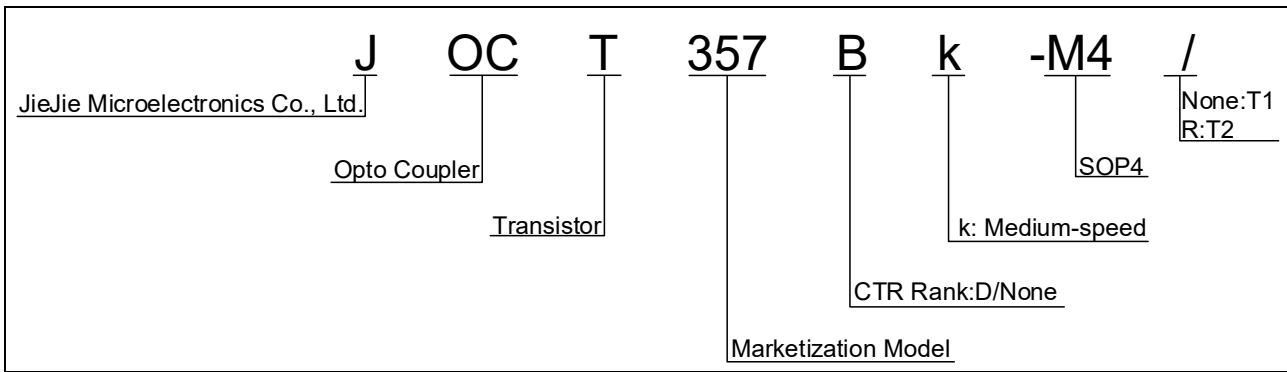
### ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =10mA	-	1.2	1.5	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> =6V	-	-	1	μA
	Terminal Capacitance	C <sub>t</sub>	V=0, f=1MHz	-	30	-	pF
Output	Collector-Emitter Dark Current	I <sub>CEO</sub>	V <sub>CE</sub> =20V	-	0.01	0.08	μA
	Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	I <sub>C</sub> =0.1mA I <sub>F</sub> =0	40	-	-	V
	Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	I <sub>E</sub> =0.1mA I <sub>F</sub> =0	7	-	-	V
	Collector-emitter Capacitance	C <sub>CE</sub>	V=0, f=1MHz	-	10	-	pF
Transfer Characteristics	Current Transfer Ratio	CTR <sup>①</sup>	I <sub>F</sub> =1mA V <sub>CE</sub> =5V	80	-	600	%
	Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> =8mA I <sub>C</sub> =2.4mA	-	-	0.3	V
	Isolation Resistance	R <sub>IO</sub>	DC500V 40~60%R.H.	10 <sup>12</sup>	10 <sup>14</sup>	-	Ω
	Floating Capacitance	C <sub>IO</sub>	V=0, f=1MHz	-	0.8	-	pF
	Cut-off Frequency	f <sub>c</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =2mA R <sub>L</sub> =100Ω, -3dB	-	80	-	kHz
Switching Characteristics	Propagation Delay Time	t <sub>PHL</sub>	V <sub>CC</sub> =5V, I <sub>F</sub> =1mA,	-	8	30	μs
		t <sub>PLH</sub>	R <sub>L</sub> =10kΩ	-	15	30	μs

**NOTE1:** Rank Table of Current Transfer Ratio (Temperature=25°C)

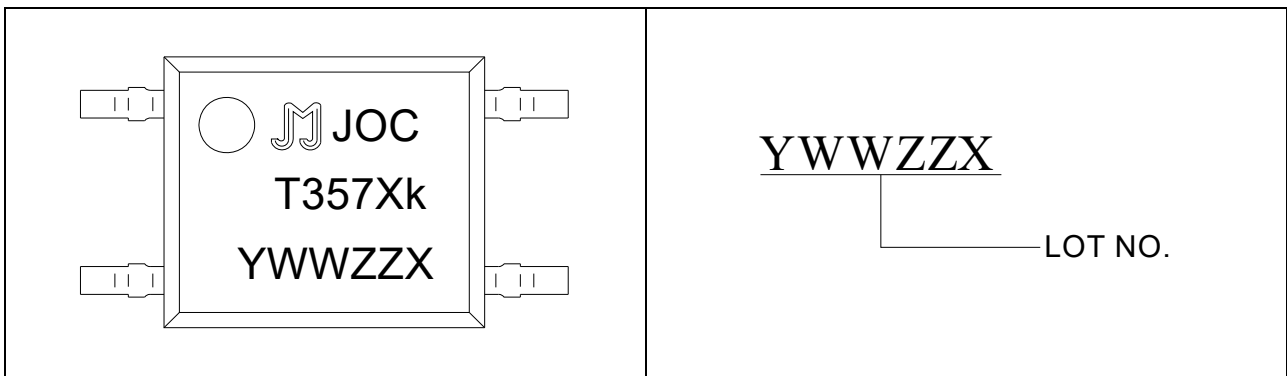
Grade Sign	Min. (%)	Max. (%)
None	80	600
D	300	600

**ORDERING INFORMATION**



Packing Quantity	
Option	Quantity
None/R	3000 Units/Reel

**MARKING**



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

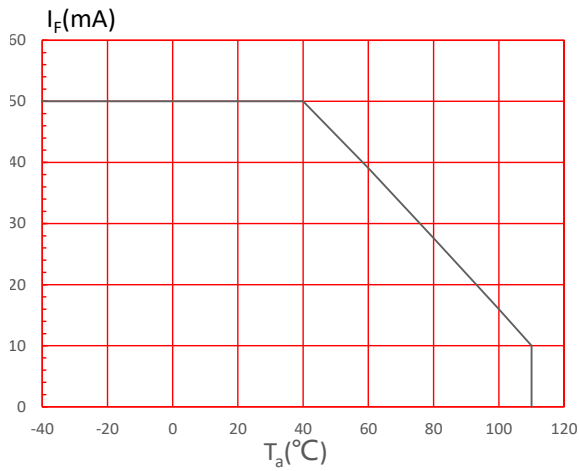


FIG.2: Collector Power Dissipation vs. Ambient Temperature

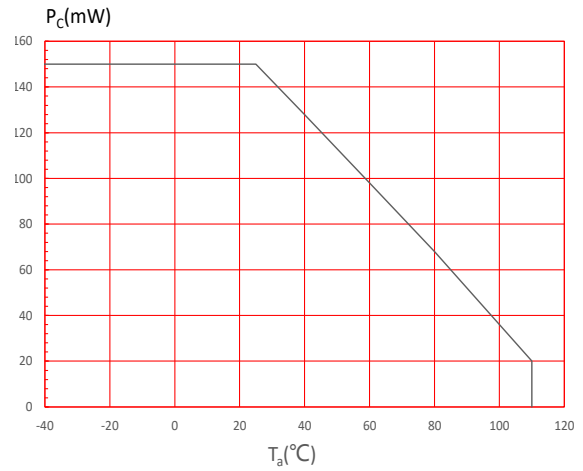


FIG.3: Forward Current vs. Forward Voltage

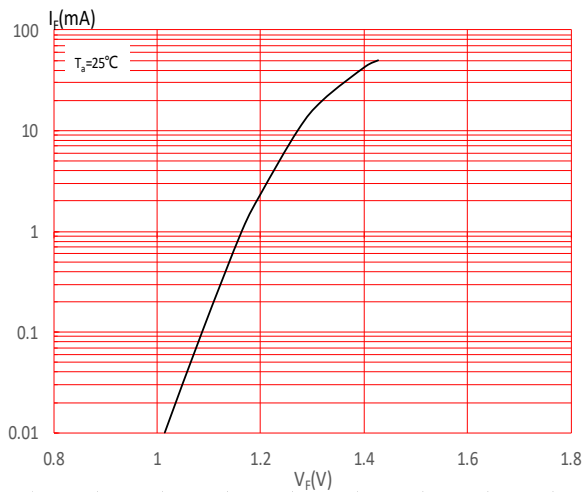


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

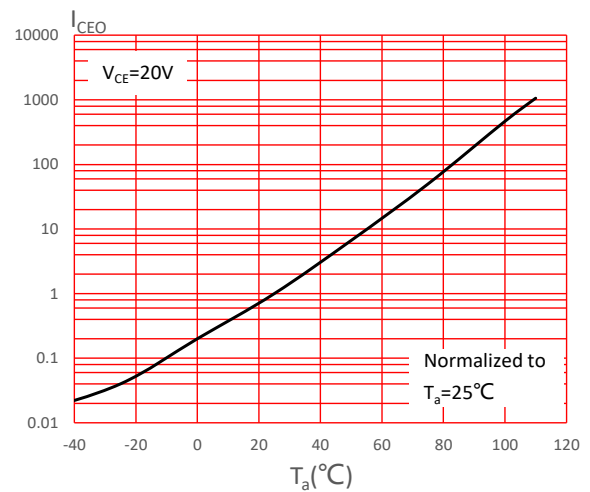


FIG.5: Collector Current vs. Collector-emitter Voltage

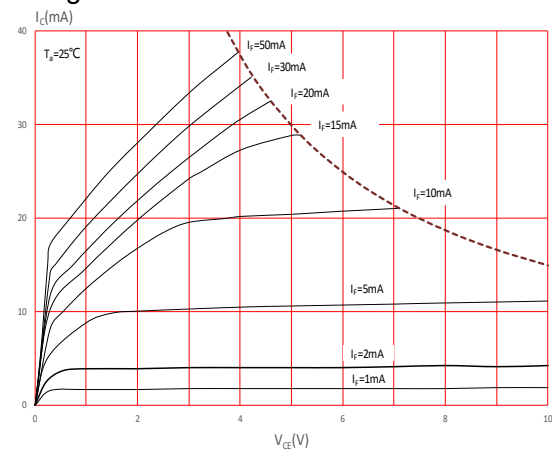
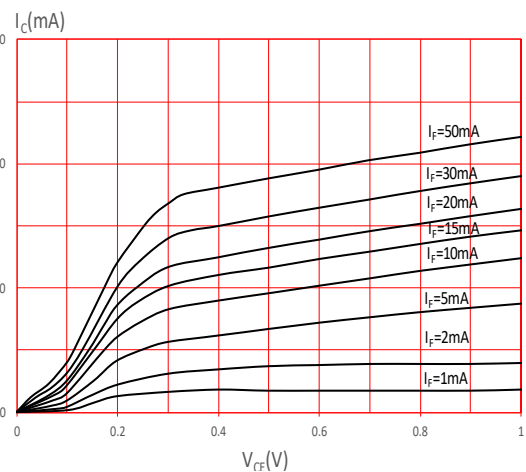
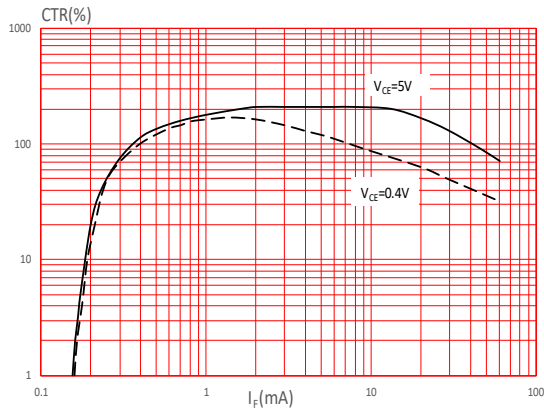


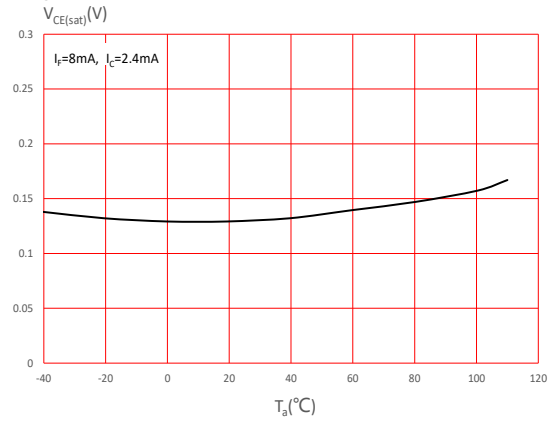
FIG.6: Collector Current vs. Collector-emitter Voltage



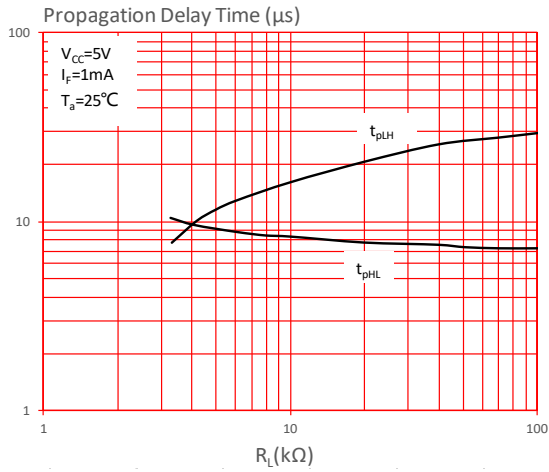
**FIG.7:** Current Transfer Ratio vs. Forward Current



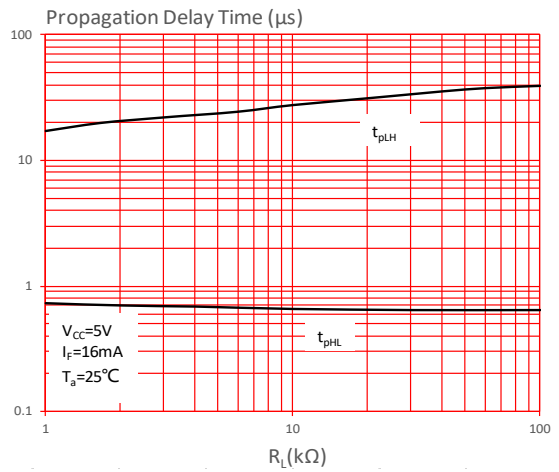
**FIG.8:** Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature



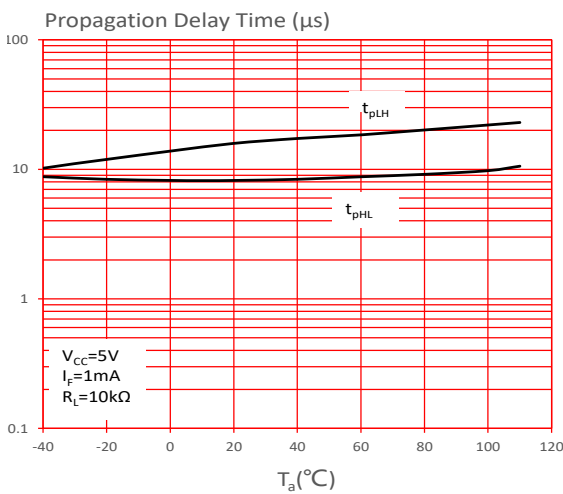
**FIG.9:** Propagation Delay Time vs. Load Resistance



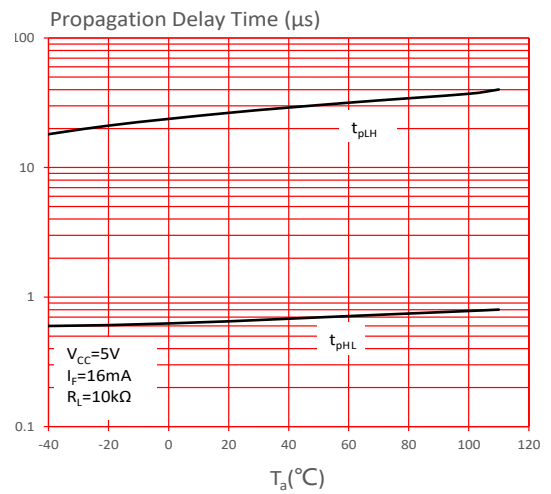
**FIG.10:** Propagation Delay Time vs. Load Resistance



**FIG.11:** Propagation Delay Time vs. Ambient Temperature



**FIG.12:** Propagation Delay Time vs. Ambient Temperature



Test Circuits

FIG.13: Test Circuits of Propagation Delay Time

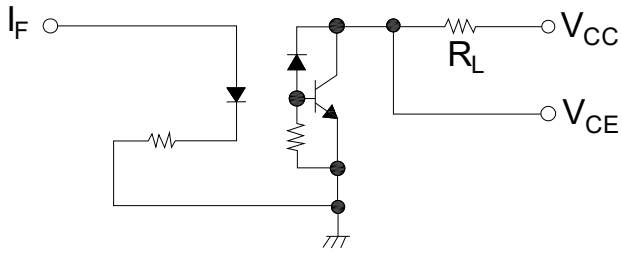
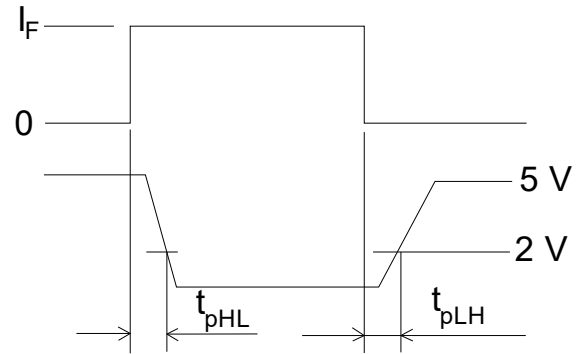
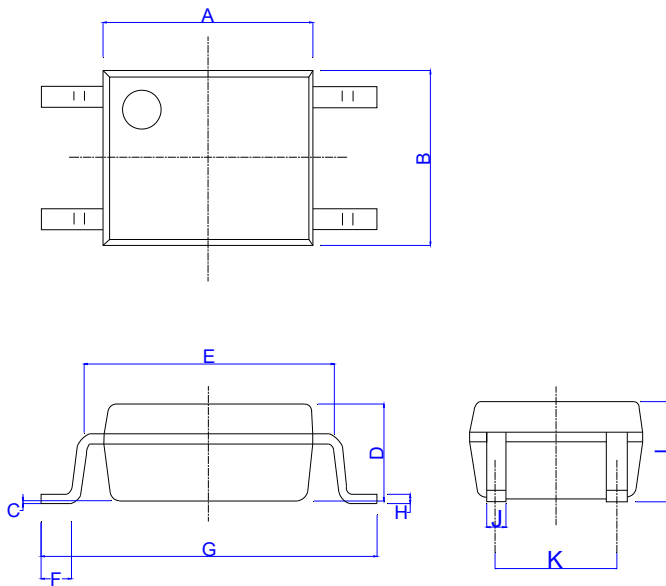


FIG.14: Curves of Propagation Delay Time

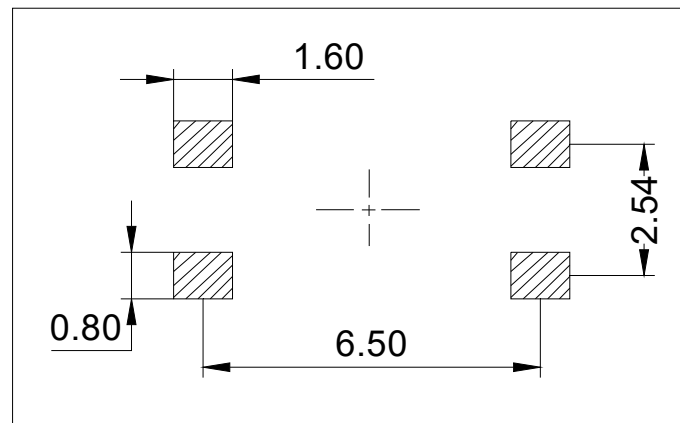


Package Dimension (Unit: mm)



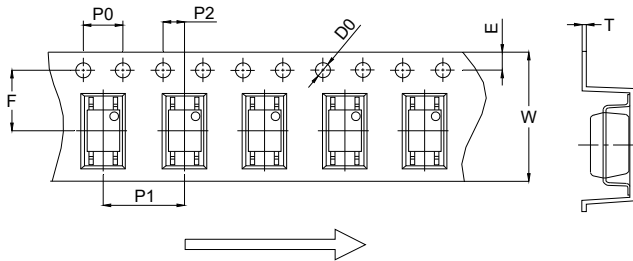
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C	0.00		0.20	0.000		0.008
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F	0.34		0.94	0.013		0.037
G	6.70		7.30	0.264		0.287
H	0.10		0.30	0.004		0.012
I	2.00		2.40	0.079		0.094
J	0.25		0.55	0.010		0.022
K	2.29		2.79	0.090		0.110

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



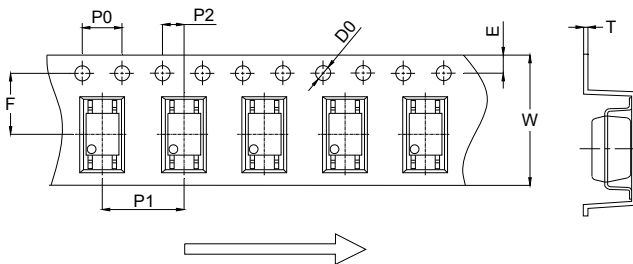
**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option None**



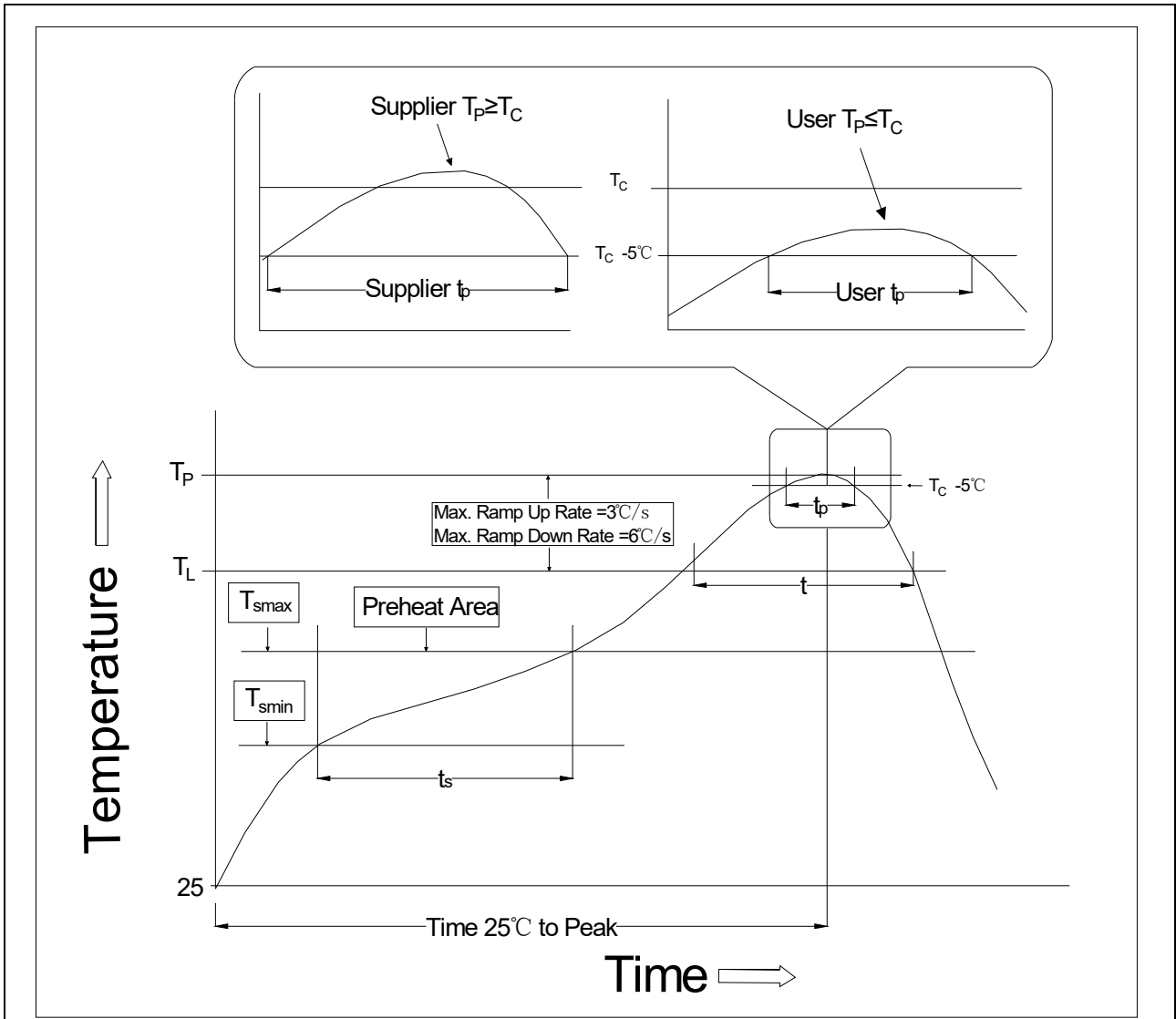
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

**Option R**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150°C
Temperature Max. (T <sub>smax</sub> )	150	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidus Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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